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Thermoplastic resin compsn. of good coatability and high flexibility - consisting of functional gp.-contg. polymer comprising specific segments, polyolefin, plasticiser and filler
Patent Assignee: KURARAY CO LTD

Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 7118492	A	19950509	JP 93285778	A	19931021	199527	B
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Patent Details

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Abstract:

JP 7118492 A

The thermoplastic resin compsn. consists of 100 pts.wt. of (a) a functional gp.- contg. polymer which consists of a segment having at least one of structural units shown by formulae (I) and -CH₂-CH₂-(II), and a segment having at least one of structural units of formulae -CH₂-CHR³-CH₂-CH₂- (3), -CH₂-CHR⁴- (4) and -CH₂-C(CH₃)₂- (5), having an average of 0.6 or more structural unit shown by formula -CR⁵R⁶-CR⁷R⁸-OH (6) at one or both terminals of molecular chain and has a number average molecular weight of 5,000- 500,000, 5-400 pts.wt. of (B) a polyolefin, 0-1,000 pts.wt. of (C) a plasticiser and 0-300 pts.wt. of (D) a filler. (C) Includes hydrocarbon oil, vegetable oil, phosphoric ester and liquid paraffin. (D) Includes calcium carbonate, clay, titanium dioxide, silica, carbon black, aluminium hydroxide, magnesium hydroxide, decabromophenyl oxide, etc.

ADVANTAGE - The thermoplastic resin compsn. has good coatability, high flexibility and mechanical strength and good processability.

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JP8269417A 19961015 HOT MELT ADHESIVE COMPOSITION Assignee/Applicant:
SEKISUI CHEMICAL CO LTD Inventor(s) : ZENKI YASUKAZU Priority (No,Kind,Date) :
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09J 123/20 A Language of Document: NotAvailable Abstract:

PURPOSE: To obtain a hot melt adhesive having a long open time, does not cause a moisture-permeable olefin resin film to undergo exudation and has a low melt viscosity.

CONSTITUTION: This composition comprises 100 pts.wt. butene-1 homopolymer and/or butene-1 copolymer, 40-300 pts.wt. tackifying resin, and 10-100 pts.wt. unsaturated hydrocarbon oligomer having a flow point of -80 to 30°C and desirably having 4-14 carbon atoms.

Legal Status: There is no Legal Status information available for this patent.